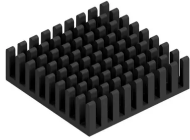


Data sheet Product ICK BGA 33 x 33 x 10



Heatsinks and active heatsinks for processors>Heatsinks for BGAs

33 x 33 x 10 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	33 mm
height:	10 mm
plate thickness:	1.8 mm
length:	33 mm
thermal resistance:	16.5 - 5.8 K/W
dissipation loss:	3.6 W
surface:	black anodised

Technical Drawing

